

ABSTRACT

A manufacturing method for a semiconductor device according to the present disclosure includes: (A) a step of preparing a structure including a substrate, a first chip disposed on the substrate, and a plurality of spacers disposed around the first chip on the substrate; (B) a step of preparing an adhesive-piece-attached chip including a second chip having a size larger than that of the first chip, and an adhesive piece provided on one face of the second chip; (C) a step of disposing the second chip above the first chip such that the adhesive piece comes into contact with the top faces of the spacers; and (D) a step of sealing the first chip, the spacers, and the second chip, and before the step (D) is carried out, the height of the top faces of the spacers coincides with the height of the top face of the first chip.

Fig. 1